

HERMETICALLY PACKAGING A MICROELECTROMECHANICAL  
SWITCH AND A FILM BULK ACOUSTIC RESONATOR

Abstract of the Disclosure

A film bulk acoustic resonator wafer and microelectro-  
mechanical switch wafer may be combined together in face-  
to-face abutment with sealing material between the wafers  
5 to define individual modules. Electrical interconnects can  
be made between the switch and the film bulk acoustic  
resonator within a hermetically sealed chamber defined  
between the switch and the film bulk acoustic resonator.